**Features:**

- n Isolated mounting base 4000V~
- n Pressure contact technology with Increased power cycling capability
- n Space and weight saving

Typical Applications

- n Various rectifiers
- n DC supply for PWM inverter

V_{RRM}	Type & Outline
2600V	MDx160-26-216F3
2800V	MDx160-28-216F3
3000V	MDx160-30-216F3
3200V	MDx160-32-216F3
3400V	MDx160-34-216F3
3600V	MDx160-36-216F3
3600V	MD160-36-216F3G

MDx stands for any type of **MDC**, **MDA**, **MDK**

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_J(^{\circ}\text{C})$	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_C=100^{\circ}\text{C}$	150			160	A
$I_{F(RMS)}$	RMS forward current					251	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			20	mA
I_{FSM}	Surge forward current	$V_R=60\%V_{RRM}$, $t=10\text{ms}$ half sine,	150			3.9	kA
I^2t	I^2t for fusing coordination					76	$10^3\text{A}^2\text{s}$
V_{FO}	Threshold voltage		150			0.84	V
r_F	Forward slope resistance					1.28	m Ω
V_{FM}	Peak forward voltage	$I_{FM}=480\text{A}$	25			1.58	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled per chip				0.23	$^{\circ}\text{C/W}$
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled per chip				0.08	$^{\circ}\text{C/W}$
V_{iso}	Isolation voltage	50Hz, R.M.S, $t=1\text{min}$, $I_{iso}=1\text{mA(MAX)}$		4000			V
F_m	Terminal connection torque(M6)			4.5		6.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T_{vj}	Junction temperature			-40		150	$^{\circ}\text{C}$
T_{stg}	Stored temperature			-40		125	$^{\circ}\text{C}$
W_t	Weight				320		g
Outline	216F3						

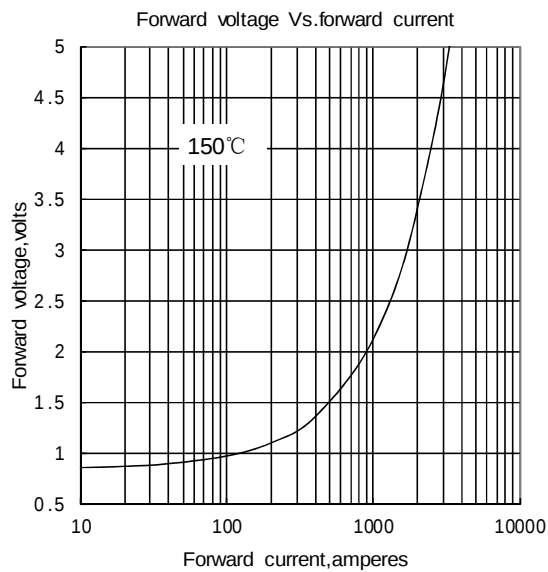


Fig.1

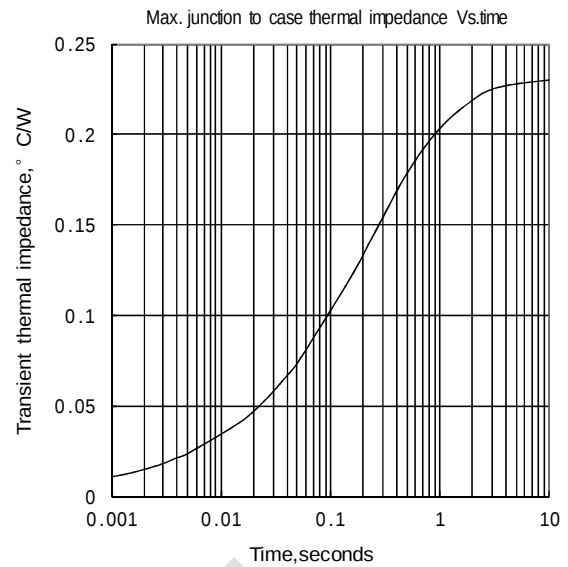


Fig.2

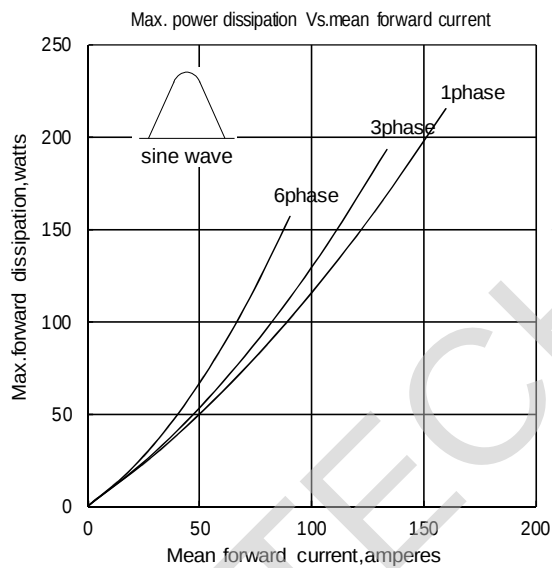


Fig.3

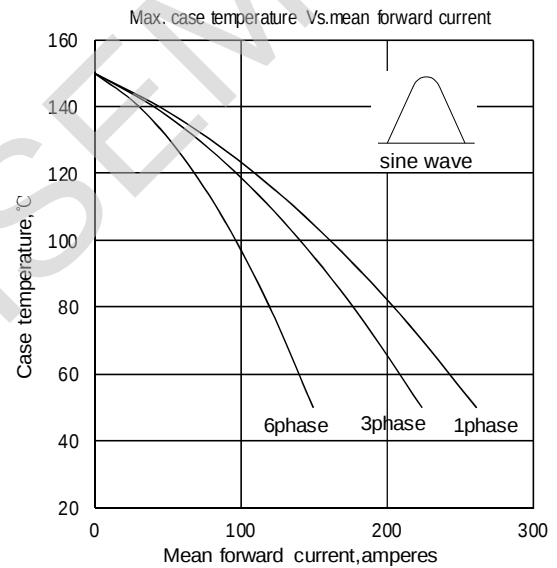


Fig.4

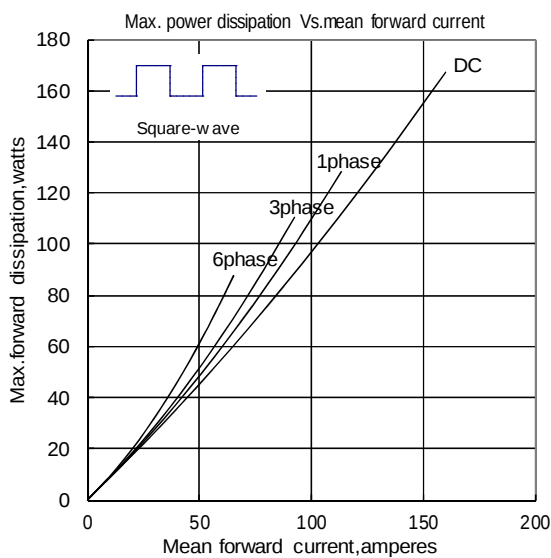


Fig.5

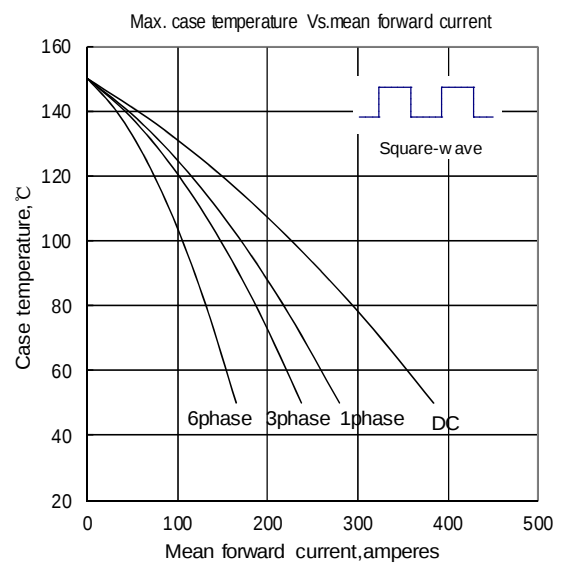


Fig.6

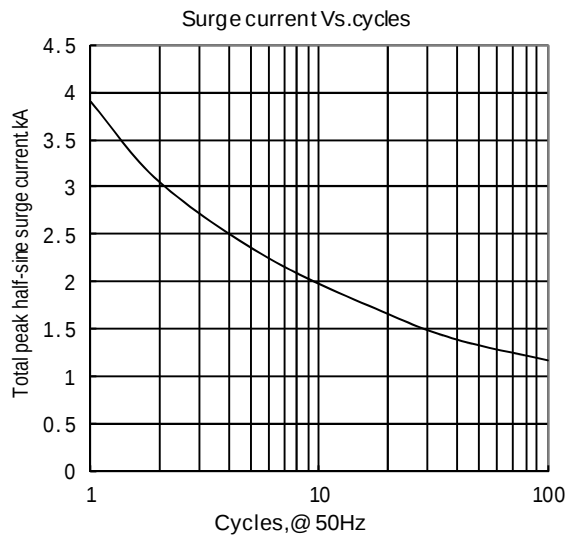


Fig. 7

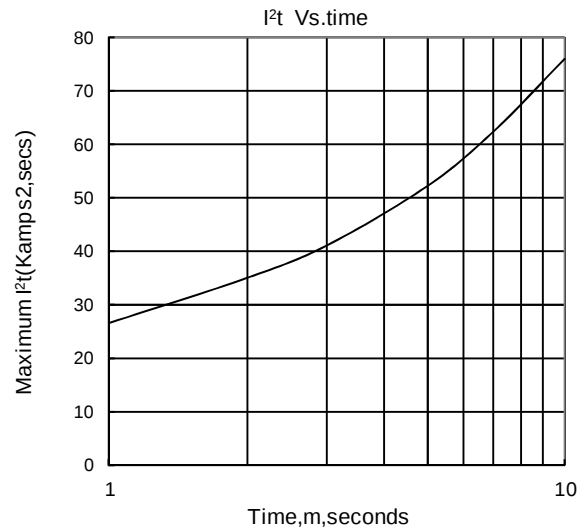
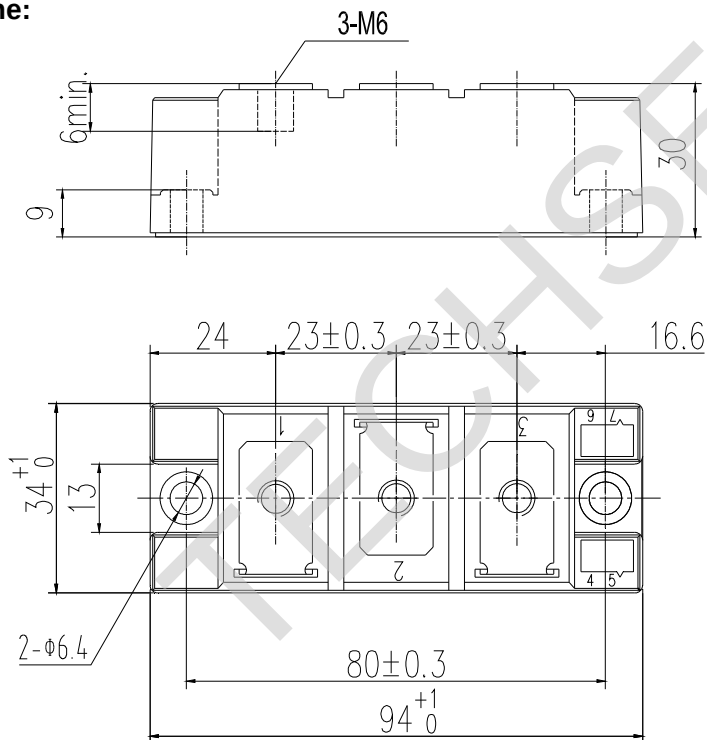


Fig. 8

Outline:Unmarked dimensional tolerance: ± 0.5 mm